

## IN THE CLAIMS

Per the revised amendment practice, a complete listing of all claims in the application follows.

Claims 1-44 (Canceled).

45. (Previously presented) A method of providing a material in a site between metal features on a wafer, comprising:

performing a deposition of said material over said wafer in said site;

and

etching said material in the same general site used to perform said deposition,

wherein said step of etching further comprises etching generally simultaneously with performing said deposition.

46. (Previously presented) The method in claim 45, wherein said step of performing a deposition further comprises depositing a polymer on said wafer.